

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>YoungJoon Kim</td><td>12/01/2008</td></tr><tr><td>Ki Youn Jang</td><td>12/01/2008</td></tr></tbody></table>	Name	Execution Date	YoungJoon Kim	12/01/2008	Ki Youn Jang	12/01/2008	
Name	Execution Date						
YoungJoon Kim	12/01/2008						
Ki Youn Jang	12/01/2008						
RECEIVING PARTY DATA							
Name:	STATS ChipPAC Ltd.						
Street Address:	10 Ang Mo Kio Street 65						
Internal Address:	#05-17/20 Techpoint						
City:	Singapore						
State/Country:	SINGAPORE						
Postal Code:	569059						
PROPERTY NUMBERS Total: 1							
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12328722</td></tr></tbody></table>	Property Type	Number	Application Number:	12328722			
Property Type	Number						
Application Number:	12328722						
CORRESPONDENCE DATA							
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NAME OF SUBMITTER:	Mikio Ishimaru						
Total Attachments: 2 source=27-586_ASSIGNMENT#page1.tif							

CH \$40.00 12328722

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PATENT
REEL: 021957 FRAME: 0447

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGING SYSTEM USING BOTTOM FLIP CHIP DIE BONDING AND METHOD OF MANUFACTURE THEREOF

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

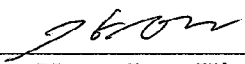
NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

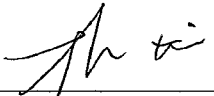
1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorize and request the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 12/328,722 Filing Date: December 4, 2008

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



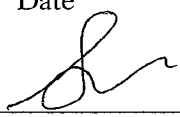
YoungJoon Kim


Witness Signature
JangHoon Shin

Print Witness Name
Dec. 1 '08

Date

Dec. 1 '08

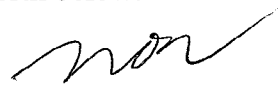
Date


Witness Signature
Sangmi Park

Print Witness Name
Dec. 1 '08

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



Ki Youn Jang


Witness Signature
JangHoon Shin

Print Witness Name
Dec. 1 '08

Date

Dec. 1. '08

Date


Witness Signature
Sangmi Park

Print Witness Name
Dec. 1 '08

Date